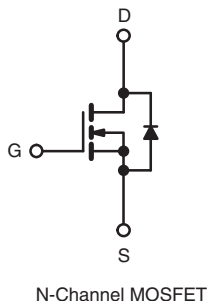
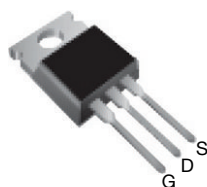


## E Series Power MOSFET

### PRODUCT SUMMARY

|                                         |                 |       |
|-----------------------------------------|-----------------|-------|
| $V_{DS}$ (V) at $T_J$ max.              | 550             |       |
| $R_{DS(on)}$ max. at 25 °C ( $\Omega$ ) | $V_{GS} = 10$ V | 0.380 |
| $Q_g$ max. (nC)                         | 50              |       |
| $Q_{gs}$ (nC)                           | 6               |       |
| $Q_{gd}$ (nC)                           | 10              |       |
| Configuration                           | Single          |       |

**TO-220AB**


### FEATURES

- Low figure-of-merit (FOM)  $R_{DS(on)} \times Q_g$
- Low input capacitance ( $C_{iss}$ )
- Reduced switching and conduction losses
- Low gate charge ( $Q_g$ )
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Computing
  - PC silver box / ATX power supplies
- Lighting
  - Two stage LED lighting
- Consumer electronics
- Applications using hard switched topologies
  - Power factor correction (PFC)
  - Two switch forward converter
  - Flyback converter
- Switch mode power supplies (SMPS)

### ORDERING INFORMATION

|                                 |                |
|---------------------------------|----------------|
| Package                         | TO-220AB       |
| Lead (Pb)-free and Halogen-free | SiHP12N50E-GE3 |

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)

| PARAMETER                                                 | SYMBOL           | LIMIT                           | UNIT |
|-----------------------------------------------------------|------------------|---------------------------------|------|
| Drain-Source Voltage                                      | $V_{DS}$         | 500                             | V    |
| Gate-Source Voltage                                       | $V_{GS}$         | $\pm 20$                        |      |
| Gate-Source Voltage AC ( $f > 1$ Hz)                      |                  | 30                              |      |
| Continuous Drain Current ( $T_J = 150$ °C)                | $V_{GS}$ at 10 V | $T_C = 25$ °C                   | A    |
|                                                           |                  | $T_C = 100$ °C                  |      |
| Pulsed Drain Current <sup>a</sup>                         | $I_{DM}$         | 21                              |      |
| Linear Derating Factor                                    |                  | 0.91                            | W/°C |
| Single Pulse Avalanche Energy <sup>b</sup>                | $E_{AS}$         | 103                             | mJ   |
| Maximum Power Dissipation                                 | $P_D$            | 114                             | W    |
| Operating Junction and Storage Temperature Range          | $T_J, T_{stg}$   | -55 to +150                     | °C   |
| Drain-Source Voltage Slope                                | $dV/dt$          | $V_{DS} = 0$ V to 80 % $V_{DS}$ | V/ns |
| Reverse Diode $dV/dt$ <sup>d</sup>                        |                  | 70                              |      |
| Soldering Recommendations (Peak Temperature) <sup>c</sup> |                  | 27                              |      |
|                                                           | for 10 s         | 300                             | °C   |

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$  V, starting  $T_J = 25$  °C,  $L = 28.2$  mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = 2.7$  A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$ ,  $dI/dt = 100$  A/ $\mu$ s, starting  $T_J = 25$  °C.

### THERMAL RESISTANCE RATINGS

| PARAMETER                        | SYMBOL     | TYP. | MAX. | UNIT |
|----------------------------------|------------|------|------|------|
| Maximum Junction-to-Ambient      | $R_{thJA}$ | -    | 62   | °C/W |
| Maximum Junction-to-Case (Drain) | $R_{thJC}$ | -    | 1.1  |      |



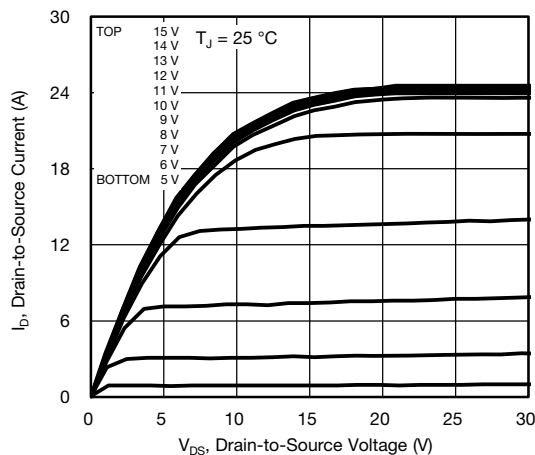
| SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted) |                                  |                                                                                                                                                       |                                               |      |       |       |      |
|-----------------------------------------------------------------|----------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------|------|-------|-------|------|
| PARAMETER                                                       | SYMBOL                           | TEST CONDITIONS                                                                                                                                       |                                               | MIN. | TYP.  | MAX.  | UNIT |
| Static                                                          |                                  |                                                                                                                                                       |                                               |      |       |       |      |
| Drain-Source Breakdown Voltage                                  | V <sub>DS</sub>                  | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA                                                                                                        |                                               | 500  | -     | -     | V    |
| V <sub>DS</sub> Temperature Coefficient                         | ΔV <sub>DS</sub> /T <sub>J</sub> | Reference to 25 °C, I <sub>D</sub> = 1 mA                                                                                                             |                                               | -    | 0.60  | -     | V/°C |
| Gate-Source Threshold Voltage (N)                               | V <sub>GS(th)</sub>              | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                                                                                           |                                               | 2.0  | -     | 4.0   | V    |
| Gate-Source Leakage                                             | I <sub>GSS</sub>                 | V <sub>GS</sub> = ± 20 V                                                                                                                              |                                               | -    | -     | ± 100 | nA   |
| Zero Gate Voltage Drain Current                                 | I <sub>DSS</sub>                 | V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V                                                                                                        |                                               | -    | -     | 1     | μA   |
|                                                                 |                                  | V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C                                                                               |                                               | -    | -     | 10    |      |
| Drain-Source On-State Resistance                                | R <sub>DS(on)</sub>              | V <sub>GS</sub> = 10 V                                                                                                                                | I <sub>D</sub> = 6 A                          | -    | 0.330 | 0.380 | Ω    |
| Forward Transconductance                                        | g <sub>fs</sub>                  | V <sub>DS</sub> = 30 V, I <sub>D</sub> = 6 A                                                                                                          |                                               | -    | 3.1   | -     | S    |
| Dynamic                                                         |                                  |                                                                                                                                                       |                                               |      |       |       |      |
| Input Capacitance                                               | C <sub>iss</sub>                 | V <sub>GS</sub> = 0 V,<br>V <sub>DS</sub> = 100 V,<br>f = 1 MHz                                                                                       |                                               | -    | 886   | -     | pF   |
| Output Capacitance                                              | C <sub>oss</sub>                 |                                                                                                                                                       |                                               | -    | 52    | -     |      |
| Reverse Transfer Capacitance                                    | C <sub>rss</sub>                 |                                                                                                                                                       |                                               | -    | 6     | -     |      |
| Effective Output Capacitance, Energy Related <sup>a</sup>       | C <sub>o(er)</sub>               | V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V                                                                                                 |                                               | -    | 45    | -     | pF   |
| Effective Output Capacitance, Time Related <sup>b</sup>         | C <sub>o(tr)</sub>               |                                                                                                                                                       |                                               | -    | 131   | -     |      |
| Total Gate Charge                                               | Q <sub>g</sub>                   | V <sub>GS</sub> = 10 V                                                                                                                                | I <sub>D</sub> = 6 A, V <sub>DS</sub> = 400 V | -    | 25    | 50    | nC   |
| Gate-Source Charge                                              | Q <sub>gs</sub>                  |                                                                                                                                                       |                                               | -    | 6     | -     |      |
| Gate-Drain Charge                                               | Q <sub>gd</sub>                  |                                                                                                                                                       |                                               | -    | 10    | -     |      |
| Turn-On Delay Time                                              | t <sub>d(on)</sub>               | V <sub>DD</sub> = 400 V, I <sub>D</sub> = 6 A,<br>V <sub>GS</sub> = 10 V, R <sub>g</sub> = 9.1 Ω                                                      |                                               | -    | 13    | 26    | ns   |
| Rise Time                                                       | t <sub>r</sub>                   |                                                                                                                                                       |                                               | -    | 16    | 32    |      |
| Turn-Off Delay Time                                             | t <sub>d(off)</sub>              |                                                                                                                                                       |                                               | -    | 29    | 58    |      |
| Fall Time                                                       | t <sub>f</sub>                   |                                                                                                                                                       |                                               | -    | 12    | 24    |      |
| Gate Input Resistance                                           | R <sub>g</sub>                   | f = 1 MHz, open drain                                                                                                                                 |                                               | -    | 0.92  | -     | Ω    |
| Drain-Source Body Diode Characteristics                         |                                  |                                                                                                                                                       |                                               |      |       |       |      |
| Continuous Source-Drain Diode Current                           | I <sub>S</sub>                   | MOSFET symbol showing the integral reverse p - n junction diode  |                                               | -    | -     | 10.5  | A    |
| Pulsed Diode Forward Current                                    | I <sub>SM</sub>                  |                                                                                                                                                       |                                               | -    | -     | 21    |      |
| Diode Forward Voltage                                           | V <sub>SD</sub>                  | T <sub>J</sub> = 25 °C, I <sub>S</sub> = 7.5 A, V <sub>GS</sub> = 0 V                                                                                 |                                               | -    | -     | 1.2   | V    |
| Reverse Recovery Time                                           | t <sub>rr</sub>                  | T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 6 A,<br>dI/dt = 100 A/μs, V <sub>R</sub> = 25 V                                             |                                               | -    | 244   | -     | ns   |
| Reverse Recovery Charge                                         | Q <sub>rr</sub>                  |                                                                                                                                                       |                                               | -    | 2.5   | -     | μC   |
| Reverse Recovery Current                                        | I <sub>RRM</sub>                 |                                                                                                                                                       |                                               | -    | 19    | -     | A    |

**Notes**

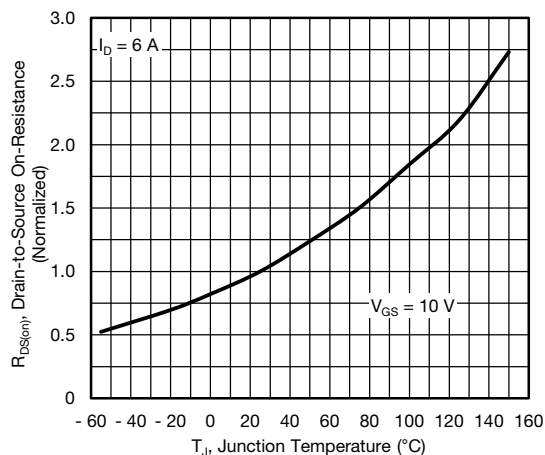
- a. C<sub>oss(er)</sub> is a fixed capacitance that gives the same energy as C<sub>oss</sub> while V<sub>DS</sub> is rising from 0 % to 80 % V<sub>DSS</sub>.  
b. C<sub>oss(tr)</sub> is a fixed capacitance that gives the same charging time as C<sub>oss</sub> while V<sub>DS</sub> is rising from 0 % to 80 % V<sub>DSS</sub>.



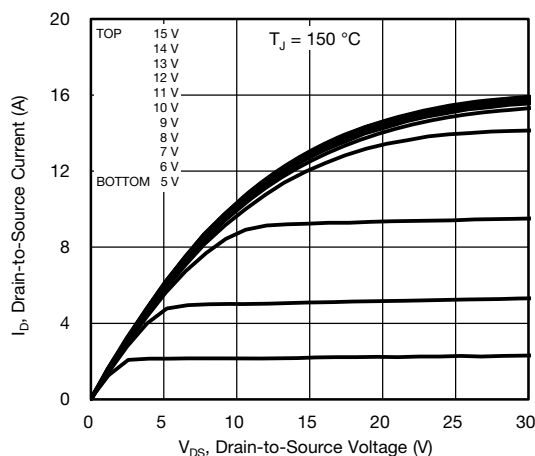
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



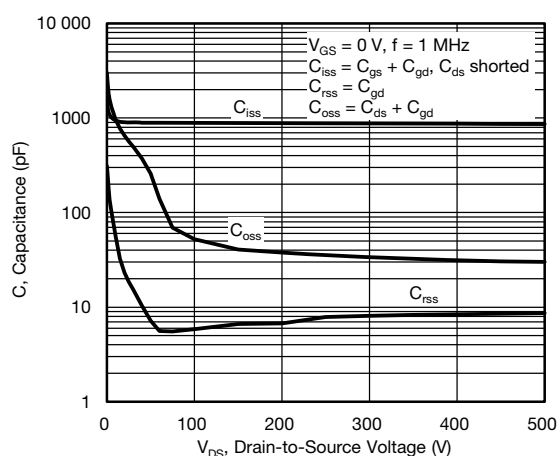
**Fig. 1 - Typical Output Characteristics**



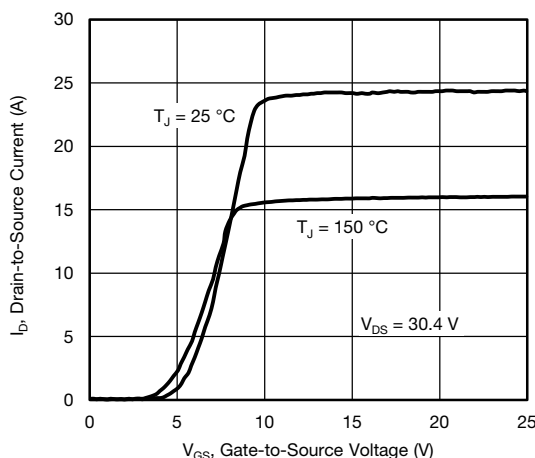
**Fig. 4 - Normalized On-Resistance vs. Temperature**



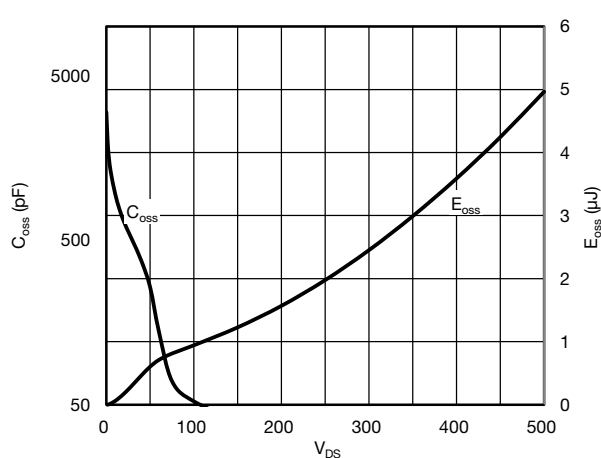
**Fig. 2 - Typical Output Characteristics**



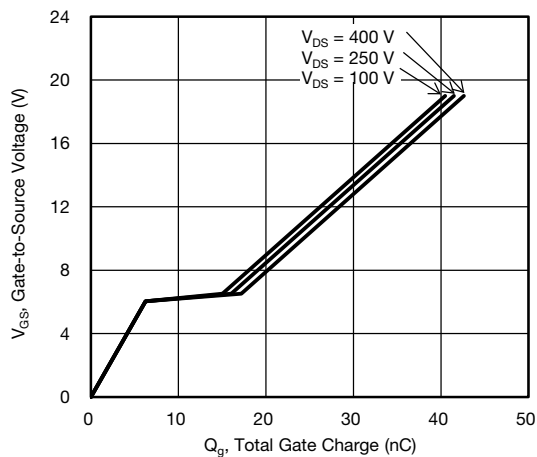
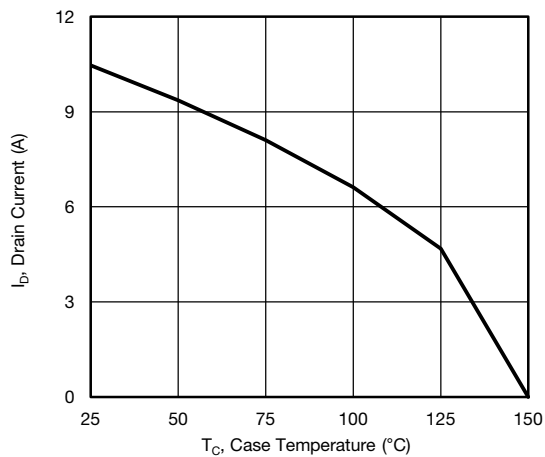
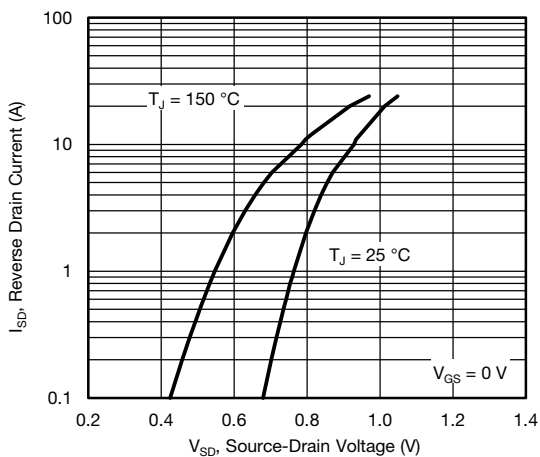
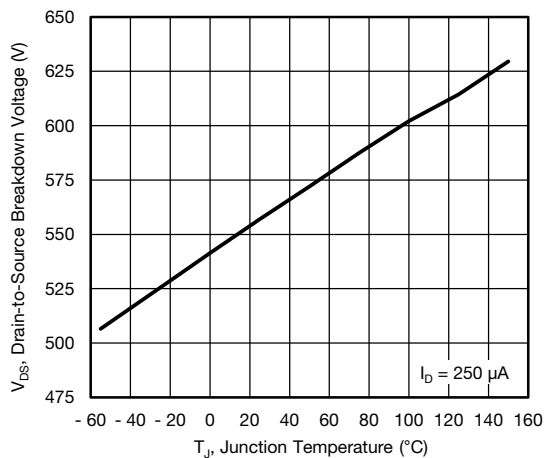
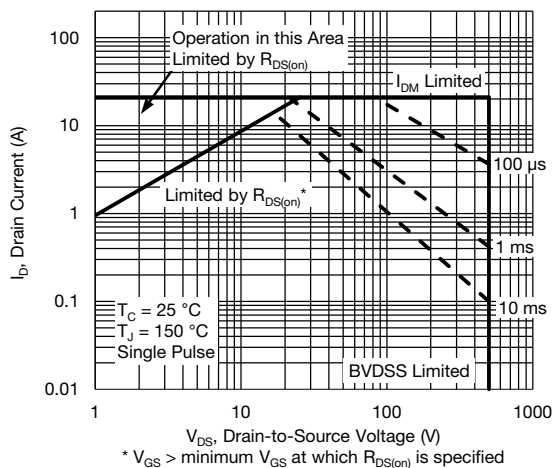
**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

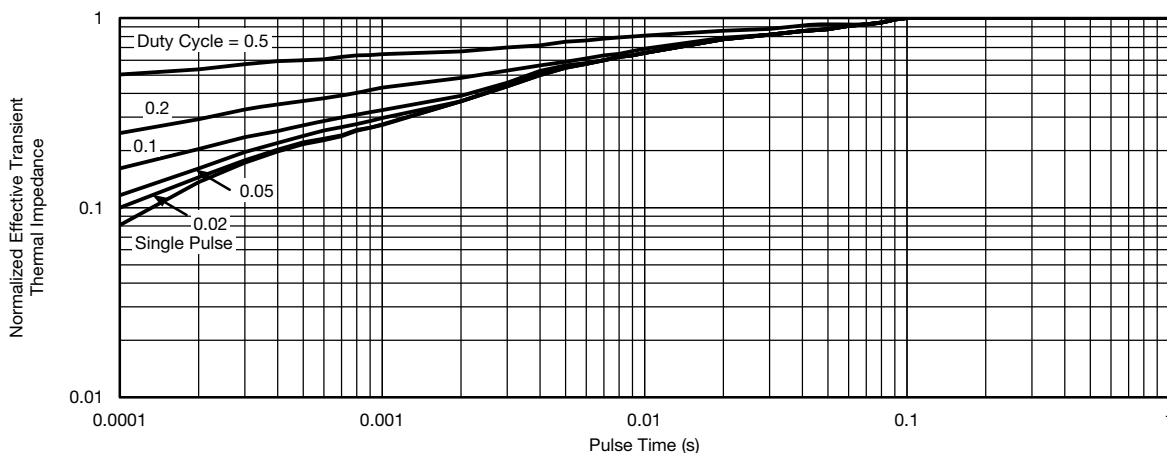
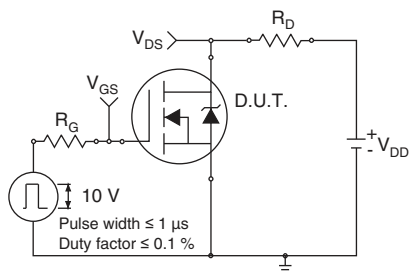
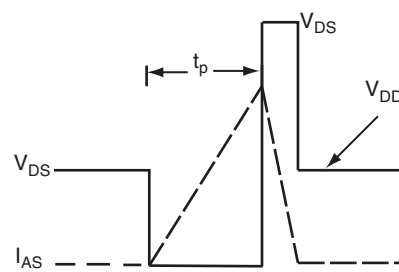
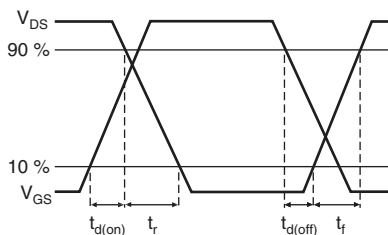
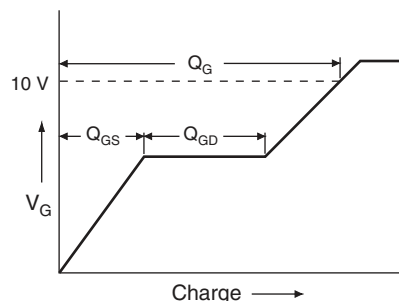
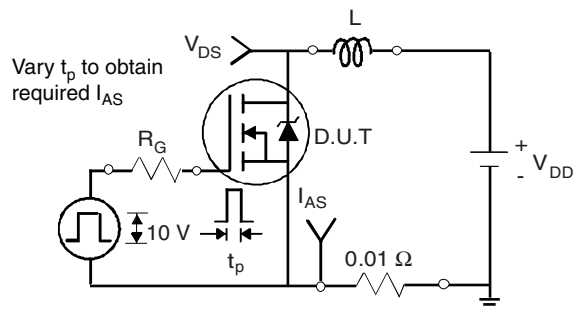
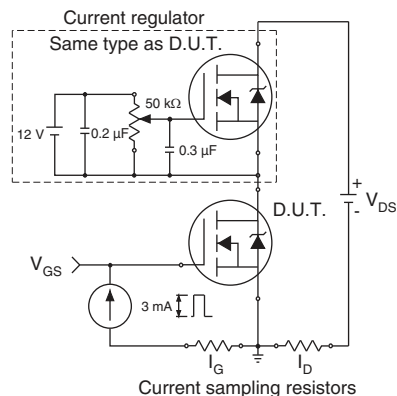


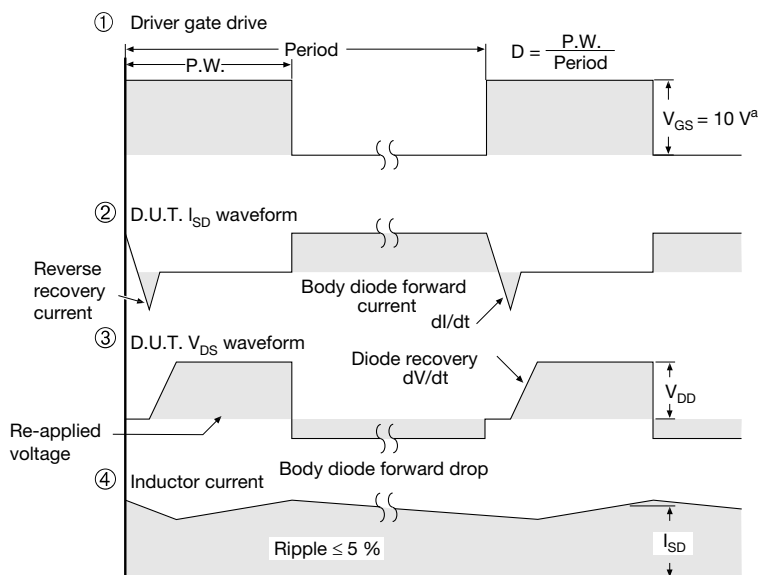
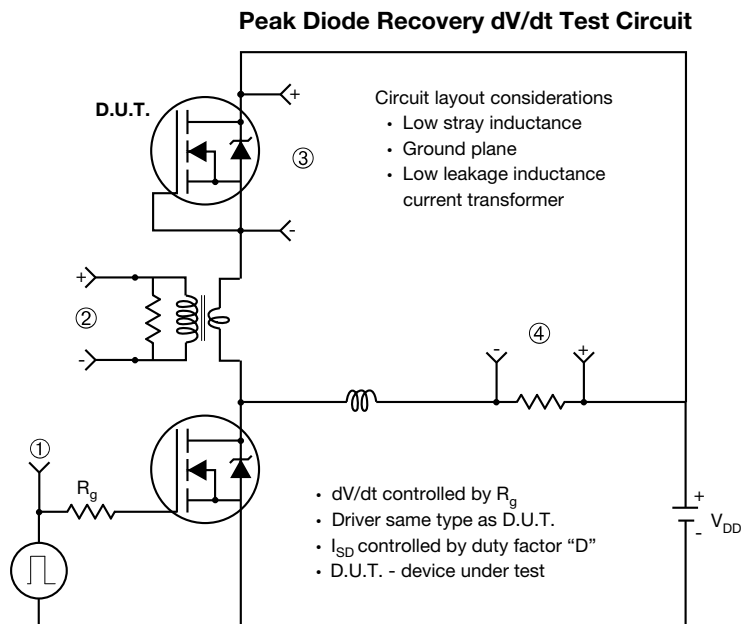
**Fig. 3 - Typical Transfer Characteristics**



**Fig. 6 - C<sub>oss</sub> and E<sub>oss</sub> vs. V<sub>DS</sub>**


**Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage**

**Fig. 10 - Maximum Drain Current vs. Case Temperature**

**Fig. 8 - Typical Source-Drain Diode Forward Voltage**

**Fig. 11 - Temperature vs. Drain-to-Source Voltage**

**Fig. 9 - Maximum Safe Operating Area**


**Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case**

**Fig. 13 - Switching Time Test Circuit**

**Fig. 16 - Unclamped Inductive Waveforms**

**Fig. 14 - Switching Time Waveforms**

**Fig. 17 - Basic Gate Charge Waveform**

**Fig. 15 - Unclamped Inductive Test Circuit**

**Fig. 18 - Gate Charge Test Circuit**


**Note**

a.  $V_{GS} = 5 V$  for logic level devices

**Fig. 19 - For N-Channel**

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